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**M24128S-FCU package mechanical data modifications**

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**Silicon identification**

This errata sheet applies to the M24128S-FCU, that is the 128 Kbit serial I<sup>2</sup>C bus EEPROM delivered in WLCSP four balls.

[Table 1](#) shows the list of part numbers.

**Table 1. Device summary**

Reference	Part Number
M24128S-FCU	M24128S-FCU6T/T, M24128S-FCU6T/TF

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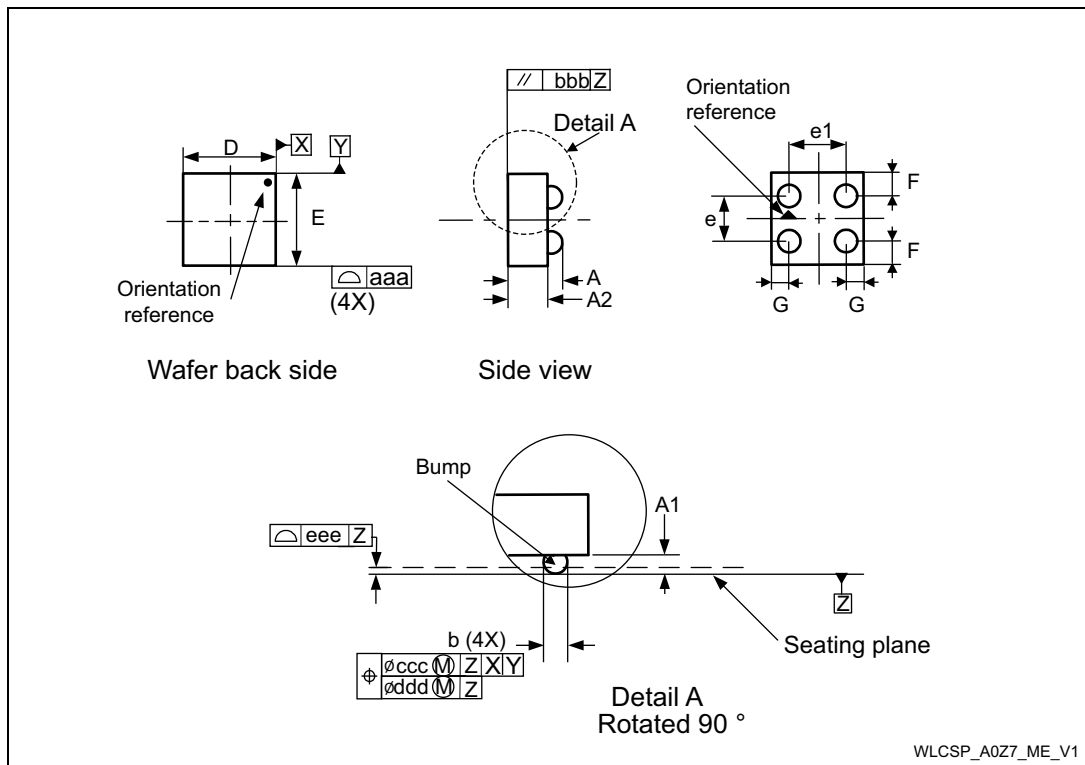
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# 1 M24128S-FCU physical product change

There isn't any physical product change.

*Figure 1* shows the package outline.

**Figure 1. Ultra Thin WLCSP- 4-bump, 0.851 x 0.851 mm, wafer level chip scale package outline**



The figures below show the difference between D and E dimension in the front side view (see *Figure 2*), back side (see *Figure 3*) and side view (see *Figure 4*).

Figure 2. D and E front side view

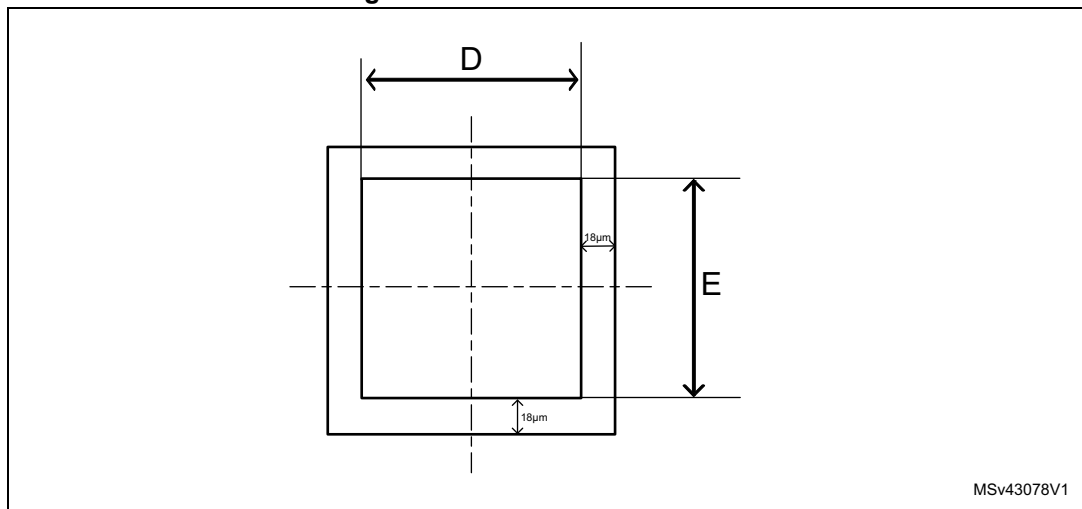


Figure 3. D and E back side view

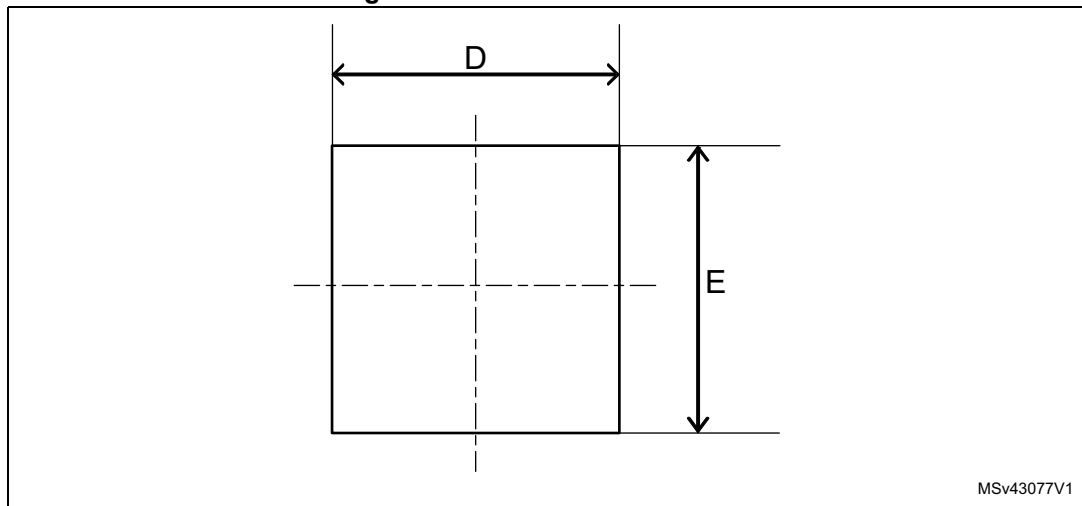
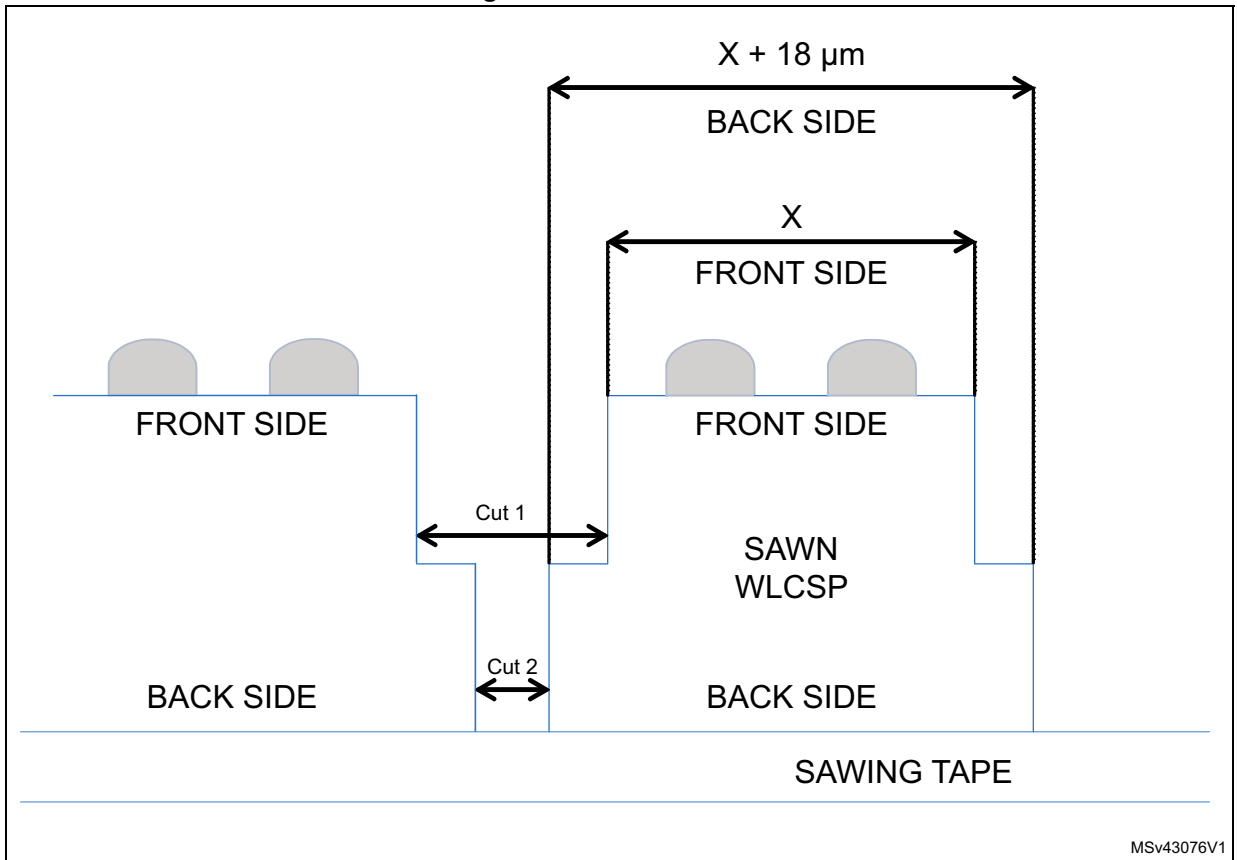


Figure 4. D or E side view



## 2 Package mechanical data modifications

This document refers to the changes of dimensions D and E (see [Figure 3](#)) described in the M24128S-FCU datasheet, in tables detailing the dimensions of the Ultra Thin WLCSP 4-bump package.

D and E values must be modified to correct the following mistake:

- The D and E values on M24128S-FCU datasheet corresponding to front side view (ball side) as shown in [Table 2](#), instead of back side view (marking side view) as shown in [Table 3](#).

**Table 2. D and E values corresponding to front side view**

Symbol	Millimeters			Inches		
	Min	Typ	Max	Min	Typ	Max
D	-	0.833	0.853	-	0.0328	0.0336
E	-	0.833	0.853	-	0.0328	0.0336

**Table 3. D and E values corresponding to back side view**

Symbol	Millimeters			Inches		
	Min	Typ	Max	Min	Typ	Max
D	0.831	0.851	0.871	0.0327	0.0335	0.0343
E	0.831	0.851	0.871	0.0327	0.0335	0.0343

The difference between back side and front side dimension is 18 µm (0.018 mm). This difference is due to two-step sawing process, where cut 1 and cut 2 are performed with blades having different thickness (see [Figure 4](#) in which X represents D or E and it has the same value and tolerance).



### 3 Revision history

Table 4. Document revision history

Date	Revision	Changes
05-Jul-2016	1	Initial release.

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